

**Series:** MEC5-DV

**Description:** High Speed Mini Edge Card Connector, Vertical, SMT Tails,  
0.5mm (.0197") Pitch, Mates with 1.60mm (.062") thick cards

### Characterization Details

This report presents data that characterizes the signal integrity response of a connector pair in a controlled printed circuit board (PCB) environment. All efforts are made to reveal typical best-case responses inherent to the system under test (SUT).

In this report, the SUT includes the connector pair and footprint effects on a typical multi-layer PCB. PCB effects (trace loss) are de-embedded from test data. Board related effects, such as pad-to-ground capacitance, are included in the data presented in this report.

Additionally, intermediate test signal connections can mask the connector's true performance. Such connection effects are minimized by using high performance test cables and adapters. Where appropriate, calibration and de-embedding routines are also used to reduce residual effects.

### Differential and Single-Ended Data

Most Samtec connectors can be used successfully in both differential and single-ended applications. However, electrical performance will differ depending on the signal drive type. In this report, data is presented for both differentially and single-ended driven scenarios.

### Connector Signal to Ground Ratio

Samtec connectors are most often designed for generic applications and can be implemented using various signal and ground pin assignments. In high-speed systems, provisions must be made in the interconnect for signal return currents. Such paths are often referred to as "ground". In some connectors, a ground plane or blade, or an outer shield, is used as the signal return, while in others, connector pins are used as signal returns. Various combinations of signal pins, ground blades, and shields can also be utilized. Electrical performance can vary significantly depending upon the number and location of ground pins.

In general, the more pins dedicated to ground, the better electrical performance will be. However, dedicating pins to ground reduces signal density of a connector. Therefore, care must be taken when choosing signal/ground ratios in cost or density-sensitive applications.



**Series:** MEC5-DV

**Description:** High Speed Mini Edge Card Connector, Vertical, SMT Tails,  
0.5mm (.0197") Pitch, Mates with 1.60mm (.062") thick cards

### Signal Edge Speed (Rise Time):

In pulse signaling applications, the perceived performance of the interconnect can vary significantly depending on the edge rate or rise time of the exciting signal. For this report, the fastest rise time used was 30 ps. Generally, this should demonstrate worst-case performance.

In many systems, the signal edge rate will be significantly slower at the connector than at the driver launch point. To estimate interconnect performance at other edge rates, data is provided for several rise times between 30ps and 500ps.

For this report, measured rise times were at 10%-90% signal levels.

### **Frequency Domain Data**

Frequency Domain parameters are helpful in evaluating the connector system's signal loss and crosstalk characteristics across a range of sinusoidal frequencies. In this report, parameters presented in the Frequency Domain are Insertion Loss, Return Loss, and Near-End and Far-End Crosstalk. Other parameters or formats, such as VSWR or S-Parameters, may be available upon request. Please contact our Signal Integrity Group at [sig@samtec.com](mailto:sig@samtec.com) for more information.

Frequency performance characteristics for the SUT are generated directly from network analyzer measurements.

### **Time Domain Data**

Time Domain parameters indicate Impedance mismatch versus length, signal propagation time, and crosstalk in a pulsed signal environment. The measured S-Parameters from the network analyzer are post-processed using Agilent Advanced Design System to obtain the time domain response. Time Domain procedure is provided in [Appendix E](#) of this report. Parameters or formats not included in this report may be available upon request. Please contact our Signal Integrity Group at [sig@samtec.com](mailto:sig@samtec.com) for more information.

In this report, propagation delay is defined as the signal propagation time through the connector and connector footprint. It includes 40 mils of PCB trace on the MEC5-DV connector and Edge Card side each. Delay is measured at 100 picoseconds signal rise time. Delay is calculated as the difference in time measured between the 50% amplitude levels of the input and output pulses.

**Series:** MEC5-DV

**Description:** High Speed Mini Edge Card Connector, Vertical, SMT Tails,  
0.5mm (.0197") Pitch, Mates with 1.60mm (.062") thick cards

Crosstalk or coupled noise data is provided for various signal configurations. All measurements are single disturber. Crosstalk is calculated as a ratio of the input line voltage to the coupled line voltage. The input line is sometimes described as the active or drive line. The coupled line is sometimes described as the quiet or victim line. Crosstalk ratio is tabulated in this report as a percentage. Measurements are made at both the near-end and far-end of the SUT.

Data for other configurations may be available. Please contact our Signal Integrity Group at [sig@samtec.com](mailto:sig@samtec.com) for further information.

As a rule of thumb, 10% crosstalk levels are often used as a general first pass limit for determining acceptable interconnect performance. However, modern system crosstalk tolerance can vary greatly. For advice on connector suitability for specific applications, please contact our Signal Integrity Group at [sig@samtec.com](mailto:sig@samtec.com).

Additional information concerning test conditions and procedures is located in the appendices of this report. Further information may be obtained by contacting our Signal Integrity Group at [sig@samtec.com](mailto:sig@samtec.com).